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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	78K/0R
Core Size	16-Bit
Speed	20MHz
Connectivity	3-Wire SIO, I ² C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/upd78f1143agb-gah-ax

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CHAPTER 4 PORT FUNCTIONS

4.1 Port Functions

There are three types of pin I/O buffer power supplies: AVREF, EVDD, and VDD. The relationship between these power supplies and the pins is shown below.

Power Supply	Corresponding Pins
AVREF	P20 to P27
EVdd	 Port pins other than P20 to P27 and P121 to P124 RESET pin and FLMD0 pin
Vdd	P121 to P124 Pins other than port pins (except RESET pin and FLMD0 pin)

Table 4-1. Pin I/O Buffer Power Sup

78K0R/KE3 products are provided with the ports shown in Figure 4-1, which enable variety of control operations. The functions of each port are shown in Table 4-2.

In addition to the function as digital I/O ports, these ports have several alternate functions. For details of the alternate functions, see **CHAPTER 2 PIN FUNCTIONS**.



Figure 4-1. Port Types

Cautions 1. Be sure to set bit 3 to 1.

- 2. The clock set by CSS, MCM0, and MDIV2 to MDIV0 is supplied to the CPU and peripheral hardware. If the CPU clock is changed, therefore, the clock supplied to peripheral hardware (except the real-time counter, clock output/buzzer output, and watchdog timer) is also changed at the same time. Consequently, stop each peripheral function when changing the CPU/peripheral operating hardware clock.
- 3. If the peripheral hardware clock is used as the subsystem clock, the operations of the A/D converter and IIC0 are not guaranteed. For the operating characteristics of the peripheral hardware, refer to the chapters describing the various peripheral hardware as well as CHAPTER 27 ELECTRICAL SPECIFICATIONS (STANDARD PRODUCTS) and CHAPTER 28 ELECTRICAL SPECIFICATIONS ((A) GRADE PRODUCTS).

The fastest instruction can be executed in 1 clock of the CPU clock in the 78K0R/KE3. Therefore, the relationship between the CPU clock (fcLK) and the minimum instruction execution time is as shown in Table 5-3.

CPU Clock	Minimum Instruction Execution Time: 1/fcLk								
(Value set by the		Main System Clo	ck (CSS = 0)	Subsystem Clock (CSS = 1)					
MDIV2 to MDIV0 bits)	High-Speed S (MCM	System Clock 0 = 1)	Internal High-Speed Oscillation Clock (MCM0 = 0)						
	At 10 MHz Operation	At 20 MHz Operation	At 8 MHz (TYP.) Operation	At 32.768 kHz Operation					
fmain	0.1 <i>μ</i> s	0.05 <i>μ</i> s	0.125 μs (TYP.)	=					
fmain/2	0.2 <i>μ</i> s	0.1 <i>μ</i> s	0.25 µs (TYP.) (default)	_					
fmain/2 ²	0.4 <i>μ</i> s	0.2 <i>µ</i> s	0.5 μs (TYP.)	_					
fmain/2 ³	0.8 μs	0.4 <i>µ</i> s	1.0 μs (TYP.)	-					
fmain/2 ⁴	1.6 <i>μ</i> s	0.8 <i>µ</i> s	2.0 μs (TYP.)	-					
fmain/2⁵	3.2 <i>μ</i> s	1.6 <i>μ</i> s	4.0 μs (TYP.)	_					
fsuв/2	_		_	61 <i>µ</i> s					

Table 5-3. Relationship Between CPU Clock and Minimum Instruction Execution Time

Remark fMAIN: Main system clock frequency (fih or fMX)

fsub: Subsystem clock frequency

(2) Example of setting procedure when using the external main system clock

<1> Setting P121/X1 and P122/X2/EXCLK pins (CMC register)

EXCLK	OSCSEL	0	OSCSELS	0	0	0	AMPH
1	1	0	0/1	0	0	0	×

Remarks 1. ×: don't care

- 2. For setting of the P123/XT1 and P124/XT2 pins, see 5.6.3 (1) Example of setting procedure when oscillating the subsystem clock.
- <2> Controlling external main system clock input (CSC register) When MSTOP is cleared to 0, the input of the external main system clock is enabled.
- Cautions 1. The CMC register can be written only once after reset release, by an 8-bit memory manipulation instruction.

Therefore, it is necessary to also set the value of the OSCSELS bits at the same time. For OSCSELS bits, see 5.6.3 Example of controlling subsystem clock.

- 2. Set the external main system clock after the supply voltage has reached the operable voltage of the clock to be used (see CHAPTER 27 ELECTRICAL SPECIFICATIONS (STANDARD PRODUCTS) and CHAPTER 28 ELECTRICAL SPECIFICATIONS ((A) GRADE PRODUCTS)).
- (3) Example of setting procedure when using high-speed system clock as CPU/peripheral hardware clock
 - <1> Setting high-speed system clock oscillation^{Note}

(See 5.6.1 (1) Example of setting procedure when oscillating the X1 clock and (2) Example of setting procedure when using the external main system clock.)

Note The setting of <1> is not necessary when high-speed system clock is already operating.

<2> Setting the high-speed system clock as the source clock of the CPU/peripheral hardware clock and setting the division ratio of the set clock (CKC register)

MCM0	MDIV2	MDIV1	MDIV0	Selection of CPU/Peripheral Hardware Clock (fcLK)
1	0	0	0	fмх
	0	0	1	f _{MX} /2
	0	1	0	f _{MX} /2 ²
	0	1	1	f _{MX} /2 ³
	1	0	0	f _{MX} /2 ⁴
	1	0	1	fmx/2 ^{5 Note}

Note Setting is prohibited when f_{MX} < 4 MHz.



Figure 6-1. Block Diagram of Timer Array Unit

(5) Sub-count register (RSUBC)

The RSUBC register is a 16-bit register that counts the reference time of 1 second of the real-time counter. It takes a value of 0000H to 7FFFH and counts 1 second with a clock of 32.768 kHz. RSUBC can be set by a 16-bit memory manipulation instruction. Reset signal generation clears this register to 0000H.

Cautions 1. When a correction is made by using the SUBCUD register, the value may become 8000H or more.

- 2. This register is also cleared by reset effected by writing the second count register.
- 3. The value read from this register is not guaranteed if it is read during operation, because a value that is changing is read.

Figure 7-6. Format of Sub-Count Register (RSUBC)

Address: FFF	90H After re	eset: 0000H	R					
Symbol	7	6	5	4	3	2	1	0
RSUBC	SUBC7	SUBC6	SUBC5	SUBC4	SUBC3	SUBC2	SUBC1	SUBC0
Address: FFF	91H After re	eset: 0000H	R					
Symbol	7	6	5	4	3	2	1	0
RSUBC	SUBC15	SUBC14	SUBC13	SUBC12	SUBC11	SUBC10	SUBC9	SUBC8

(6) Second count register (SEC)

The SEC register is an 8-bit register that takes a value of 0 to 59 (decimal) and indicates the count value of seconds.

It counts up when the sub-counter overflows.

When data is written to this register, it is written to a buffer and then to the counter up to 2 clocks (32.768 kHz) later. Set a decimal value of 00 to 59 to this register in BCD code. If a value outside the range is set, the register value returns to the normal value after 1 period.

SEC can be set by an 8-bit memory manipulation instruction.

Reset signal generation clears this register to 00H.

Figure 7-7. Format of Second Count Register (SEC)

Address: FFF92H After reset: 00H R/W

Symbol	7	6	5	4	3	2	1	0
SEC	0	SEC40	SEC20	SEC10	SEC8	SEC4	SEC2	SEC1

10.4 A/D Converter Operations

10.4.1 Basic operations of A/D converter

- <1> Set bit 5 (ADCEN) of peripheral enable register 0 (PER0) to 1 to start the supply of the input clock to the A/D converter.
- <2> Set bit 0 (ADCE) of the A/D converter mode register (ADM) to 1 to start the operation of the comparator.
- <3> Set channels for A/D conversion to analog input by using bits the A/D port configuration register (ADPC) and set to input mode by using port mode registers 2 (PM2).
- <4> Set A/D conversion time by using bits 5 to 1 (FR2 to FR0, LV1, and LV0) of ADM.
- <5> Select one channel for A/D conversion using the analog input channel specification register (ADS).
- <6> Start the conversion operation by setting bit 7 (ADCS) of ADM to 1. (<7> to <13> are operations performed by hardware.)
- <7> The voltage input to the selected analog input channel is sampled by the sample & hold circuit.
- <8> When sampling has been done for a certain time, the sample & hold circuit is placed in the hold state and the sampled voltage is held until the A/D conversion operation has ended.
- <9> Bit 9 of the successive approximation register (SAR) is set. The series resistor string voltage tap is set to (1/2) AVREF by the tap selector.
- <10> The voltage difference between the series resistor string voltage tap and sampled voltage is compared by the voltage comparator. If the analog input is greater than (1/2) AVREF, the MSB of SAR remains set to 1. If the analog input is smaller than (1/2) AVREF, the MSB is reset to 0.
- <11> Next, bit 8 of SAR is automatically set to 1, and the operation proceeds to the next comparison. The series resistor string voltage tap is selected according to the preset value of bit 9, as described below.
 - Bit 9 = 1: (3/4) AVREF
 - Bit 9 = 0: (1/4) AVREF

The voltage tap and sampled voltage are compared and bit 8 of SAR is manipulated as follows.

- Analog input voltage ≥ Voltage tap: Bit 8 = 1
- Analog input voltage < Voltage tap: Bit 8 = 0
- <12> Comparison is continued in this way up to bit 0 of SAR.
- <13> Upon completion of the comparison of 10 bits, an effective digital result value remains in SAR, and the result value is transferred to the A/D conversion result register (ADCR, ADCRH) and then latched. At the same time, the A/D conversion end interrupt request (INTAD) can also be generated.

<14> Repeat steps <7> to <13>, until ADCS is cleared to 0.

To stop the A/D converter, clear ADCS to 0.

To restart A/D conversion from the status of ADCE = 1, start from <6>. To start A/D conversion again when ADCE = 0, set ADCE to 1, wait for 1 μ s or longer, and start <6>. To change a channel of A/D conversion, start from <5>.

Caution Make sure the period of <2> to <6> is 1 μ s or more.

- **Remark** Two types of A/D conversion result registers are available.
 - ADCR (16 bits): Store 10-bit A/D conversion value
 - ADCRH (8 bits): Store 8-bit A/D conversion value

(8) Serial channel enable status register m (SEm)

SEm indicates whether data transmission/reception operation of each channel is enabled or stopped.

When 1 is written a bit of serial channel start register m (SSm), the corresponding bit of this register is set to 1. When 1 is written a bit of serial channel stop register m (STm), the corresponding bit is cleared to 0.

Channel n that is enabled to operate cannot rewrite by software the value of CKOmn of the serial output register m (SOm) to be described below, and a value reflected by a communication operation is output from the serial clock pin.

Channel n that stops operation can set the value of CKOmn of the SOm register by software and output its value from the serial clock pin. In this way, any waveform, such as that of a start condition/stop condition, can be created by software.

SEm can be read by a 16-bit memory manipulation instruction.

The lower 8 bits of SEm can be set with an 1-bit or 8-bit memory manipulation instruction with SEmL. Reset signal generation clears this register to 0000H.

Figure 11-11. Format of Serial Channel Enable Status Register m (SEm)

Address: F01	20H, F()121H	After	reset: 0	000H	R										
Symbol	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SE0	0	0	0	0	0	0	0	0	0	0	0	0	SE0	SE0	SE0	SE0
													3	2	1	0
Address: F01	60H, F0	0161H	After	reset: 0	000H	R										
Symbol	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
SE1	0	0	0	0	0	0	0	0	0	0	0	0	SE1	SE1	0	0
													3	2		
	SEm				lı	ndicatio	n of ope	eration e	enable/s	stop sta	tus of c	hannel	n			
	n															
	0	Opera	tion sto	ps (stop	os with	the valu	es of th	e contro	ol regist	ter and	shift reg	jister, a	nd the s	statuses	s of the	serial

clock I/O pin, serial data output pin, and the FEF, PEF, and OVF error flags retained^{Note}).

1 Operation is enabled.

Note Bits 6 and 5 (TSFmn, BFFmn) of the SSRmn register are cleared.

Remark m: Unit number (m = 0, 1), n: Channel number (n = 0 to 3), mn = 00 to 03, 12, 13

Figure 11-51. Procedure for Resuming Slave Transmission



<R>

(2) Operation procedure



Figure 11-57. Initial Setting Procedure for Slave Reception

Caution After setting the PER0 register to 1, be sure to set the SPS0 register after 4 or more clocks have elapsed.





Write 1 to the ST0n bit of the target channel.

Stop communication in midway.

SPT0	Stop condition trigger							
0	Stop condition is not generated.							
1	Stop condition is generated (termination of master device's transfer). After the SDA0 line goes to low level, either set the SCL0 line to high level or wait until it goes to high level. Next, after the rated amount of time has elapsed, the SDA0 line changes from low level to high level and a stop condition is generated.							
Cautions concerning set timing • For master reception: Cannot be set to 1 during transfer. Can be set to 1 only in the waiting period when ACKE0 has been cleared to 0 and slave								
 For master 	er transmission: A stop condition cannot be ger set it during the wait period that	nerated normally during the acknowledge period. Therefore, t follows output of the ninth clock.						
Cannot be CDTO as a	e set to 1 at the same time as STT0.							
When WT note that a changed f the wait p Setting SF	 SPT0 can be set to 1 only when in master mode^{Note}. When WTIM0 has been cleared to 0, if SPT0 is set to 1 during the wait period that follows output of eight clocks, note that a stop condition will be generated during the high-level period of the ninth clock. WTIM0 should be changed from 0 to 1 during the wait period following the output of eight clocks, and SPT0 should be set to 1 during the wait period that follows the output of the ninth clock. Setting SPT0 to 1 and then setting it again before it is cleared to 0 is prohibited. 							
Condition for	or clearing (SPT0 = 0)	Condition for setting (SPT0 = 1)						
 Cleared b Automatic Cleared b When IICI Reset 	y loss in arbitration ally cleared after stop condition is detected y LREL0 = 1 (exit from communications) E0 = 0 (operation stop)	Set by instruction						

Figure 12-6. Format of IIC Control Register 0 (IICC0) (4/4)

- **Note** Set SPT0 to 1 only in master mode. However, SPT0 must be set to 1 and a stop condition generated before the first stop condition is detected following the switch to the operation enabled status.
- Caution When bit 3 (TRC0) of IIC status register 0 (IICS0) is set to 1, WREL0 is set to 1 during the ninth clock and wait is canceled, after which TRC0 is cleared and the SDA0 line is set to high impedance.
- **Remark** Bit 0 (SPT0) becomes 0 when it is read after data setting.

12.5 I²C Bus Definitions and Control Methods

The following section describes the I²C bus's serial data communication format and the signals used by the I²C bus. Figure 12-13 shows the transfer timing for the "start condition", "address", "data", and "stop condition" output via the I²C bus's serial data bus.





The master device generates the start condition, slave address, and stop condition.

The acknowledge (ACK) can be generated by either the master or slave device (normally, it is output by the device that receives 8-bit data).

The serial clock (SCL0) is continuously output by the master device. However, in the slave device, the SCL0's low level period can be extended and a wait can be inserted.

12.5.1 Start conditions

A start condition is met when the SCL0 pin is at high level and the SDA0 pin changes from high level to low level. The start conditions for the SCL0 pin and SDA0 pin are signals that the master device generates to the slave device when starting a serial transfer. When the device is used as a slave, start conditions can be detected.





A start condition is output when bit 1 (STT0) of IIC control register 0 (IICC0) is set (to 1) after a stop condition has been detected (SPD0: Bit 0 = 1 in IIC status register 0 (IICS0)). When a start condition is detected, bit 1 (STD0) of IICS0 is set (to 1).

Standard Products

Absolute Maximum Ratings $(T_A = 25^{\circ}C)$ (2/2)

Parameter	Symbols		Conditions	Ratings	Unit
Output current, high	Юнт	Per pin	P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P70 to P77, P120, P130, P140, P141	-10	mA
		Total of all pins –80 mA	P00 to P04, P40 to P43, P120, P130, P140, P141	-25	mA
			P05, P06, P10 to P17, P30, P31, P50 to P55, P70 to P77	-55	mA
	Іон2	Per pin	P20 to P27	-0.5	mA
		Total of all pins		-2	mA
Output current, low	Iol1	Per pin	P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P60 to P63, P70 to P77, P120, P130, P140, P141	30	mA
		Total of all pins 200 mA	P00 to P04, P40 to P43, P120, P130, P140, P141	60	mA
			P05, P06, P10 to P17, P30, P31, P50 to P55, P60 to P63, P70 to P77	140	mA
	IOL2	Per pin	P20 to P27	1	mA
		Total of all pins		5	mA
Operating ambient	Та	In normal operation	on mode	-40 to +85	°C
temperature		In flash memory	programming mode		
Storage temperature	Tstg			-65 to +150	°C

- Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.
- **Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

Standard Products

DC Characteristics (10/10)

$(TA = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le \text{V}\text{dd} = \text{EV}\text{dd} \le 5.5 \text{ V}, 1.8 \text{ V} \le \text{AV}\text{Ref} \le \text{V}\text{dd}, \text{V}\text{ss} = \text{EV}\text{ss} = \text{AV}\text{ss} = 0 \text{ V})$

Parameter	Symbol	Conditions			TYP.	MAX.	Unit
RTC operating	RTC ^{Notes 1, 2}	fsuв = 32.768 kHz	$V_{DD} = 3.0 V$		0.2	1.0	μA
current			V _{DD} = 2.0 V		0.2	1.0	
Watchdog timer operating current	Watchdog timer operating current $I_{WDT}^{Notes 2, 3}$ $f_{IL} = 240 \text{ kHz}$				5	10	μA
A/D converter operating current	IADC ^{Note 4}	During conversion at maximum speed, 2.3 V \leq AV_{REF}		0.86	1.9	mA	
LVI operating ILVI ^{Note 5} current				9	18	μA	

Notes 1. Current flowing only to the real-time counter (excluding the operating current of the XT1 oscillator). The current value of the 78K0R/KE3 is the TYP. value, the sum of the TYP. values of either IDD1 or IDD2, and IRTC, when the real-time counter operates in operation mode or HALT mode. The IDD1 and IDD2 MAX. values also include the real-time counter operating current.

- 2. When internal high-speed oscillator and high-speed system clock are stopped.
- **3.** Current flowing only to the watchdog timer (including the operating current of the 240 kHz internal oscillator). The current value of the 78K0R/KE3 is the sum of IDD1, I DD2 or I DD3 and IwDT when fcLK = fsUB/2 or when the watchdog timer operates in STOP mode.
- **4.** Current flowing only to the A/D converter (AV_{REF} pin). The current value of the 78K0R/KE3 is the sum of IDD1 or IDD2 and IADC when the A/D converter operates in an operation mode or the HALT mode.
- 5. Current flowing only to the LVI circuit. The current value of the 78K0R/KE3 is the sum of IDD1, IDD2 or IDD3 and ILVI when the LVI circuit operates in the Operating, HALT or STOP mode.
- Remarks 1.
 fil:
 Internal low-speed oscillation clock frequency

 fsub:
 Subsystem clock frequency (XT1 clock oscillation frequency)

 fcLk:
 CPU/peripheral hardware clock frequency
 - **2.** Temperature condition of the TYP. value is $T_A = 25^{\circ}C$

724

<R>

(2) Serial interface: Serial array unit (3/18)

<R>

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 1.8 \text{ V} \le \text{V}_{DD} = \text{EV}_{DD} \le 5.5 \text{ V}, \text{V}_{SS} = \text{EV}_{SS} = \text{AV}_{SS} = 0 \text{ V})$

Parameter	Symbol	Con	ditions	MIN.	TYP.	MAX.	Unit
SCKp cycle time	tксү2	$4.0~V \le V_{\text{DD}} \le 5.5$	V	6/fмск			ns
		$2.7 \text{ V} \leq \text{V}_{\text{DD}} < 4.0$	V 16 MHz < fмс	к 8/fмск			ns
			fмск ≤ 16 MH	z 6/fмск			ns
		$1.8 \text{ V} \le \text{V}_{\text{DD}} < 2.7$	V 16 MHz < fмс	к 8/fмск			ns
	Г МСК		fмск ≤ 16 MH	z 6/fмск			ns
SCKp high-/low-level width	tкн2,			fксү2/2			ns
	tĸ∟2						
SIp setup time (to SCKp↑) ^{Note 1}	tsik2			80			ns
SIp hold time (from SCKp↑) ^{Note 2}	t หรเ2			1/fмск + 50			ns
Delay time from $\overline{\mathrm{SCKp}}\downarrow$ to	tĸso2	C = 30 pF ^{Note 4}	$4.0 \text{ V} \leq V_{\text{DD}} \leq 5.5 \text{ V}$	/		2/fмск + 45	ns
SOp output ^{Note 3}			$2.7 \text{ V} \leq \text{V}_{\text{DD}} < 4.0 $	/		2/fмск + 57	ns
			$1.8 \text{ V} \le \text{V}_{\text{DD}} < 2.7$	/		2/fмск + 125	ns

(c) During communication at same potential (CSI mode) (slave mode, SCKp... external clock input)

Notes 1. When DAP0n = 0 and CKP0n = 0, or DAP0n = 1 and CKP0n = 1. The SIp setup time becomes "to \overline{SCKp} [↑]" when DAP0n = 0 and CKP0n = 1, or DAP0n = 1 and CKP0n = 0.

- **2.** When DAP0n = 0 and CKP0n = 0, or DAP0n = 1 and CKP0n = 1. The SIp setup time becomes "from $\overline{SCKp}\downarrow$ " when DAP0n = 0 and CKP0n = 1, or DAP0n = 1 and CKP0n = 0.
- **3.** When DAP0n = 0 and CKP0n = 0, or DAP0n = 1 and CKP0n = 1. The delay time to SOp output becomes "from $\overline{SCKp}\downarrow$ " when DAP0n = 0 and CKP0n = 1, or DAP0n = 1 and CKP0n = 0.
- 4. C is the load capacitance of the SOp output line.

Caution When using CSI10, select the normal input buffer for SI10 and SCK10 and the normal output mode for SO10 by using the PIM0 and POM0 registers.

Remarks 1. p: CSI number (p = 00, 10)

 fMCK: Serial array unit operation clock frequency (Operation clock to be set by the CKS0n bit of the SMR0n register. n: Channel number (n = 0, 2))

Standard Products

(2) Serial interface: Serial array unit (18/18)

Simplified I²C mode connection diagram (during communication at different potential)



Simplified I²C mode serial transfer timing (during communication at different potential)



Caution Select the TTL input buffer and the N-ch open drain output (VDD tolerance) mode for SDA10 and the N-ch open drain output (VDD tolerance) mode for SCL10 by using the PIM0 and POM0 registers.

Remark R_b[Ω]:Communication line (SDA10, SCL10) pull-up resistance, V_b[V]: Communication line voltage

(A) Grade Products

DC Characteristics (1/10)

(TA = -40 to +85°C	$3.1.8 \text{ V} \leq \text{V}_{\text{DD}} = \text{EV}_{\text{DD}} \leq 5.5$	$V, 1.8 V \le AV_{REF} \le V_{DD}$, Vss = EVss = AVss = 0 V)
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Items	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Output current,	Іон1	Per pin for P00 to P06, P10 to P17, P30, P31, P40 to P43, P50 to P55, P70 to P77, P120, P130, P140, P141	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			-3.0	mA
high ^{Note 1}			$2.7~V \leq V_{\text{DD}} < 4.0~V$			-1.0	mA
			$1.8~V \leq V_{\text{DD}} < 2.7~V$			-1.0	mA
		Total of P00 to P04, P40 to P43, P120, P130, P140, P141 (When duty = $70\%^{Note 2}$) Total of P05, P06, P10 to P17, P30, P31, P50 to P55, P70 to P77 (When duty = $70\%^{Note 2}$) Total of all pins (When duty = $60\%^{Note 2}$)	$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			-12.0	mA
			$2.7~V \leq V_{\text{DD}} < 4.0~V$			-7.0	mA
			$1.8~V \leq V_{\text{DD}} < 2.7~V$			-5.0	mA
			$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			-18.0	mA
			$2.7~V \leq V_{\text{DD}} < 4.0~V$			-15.0	mA
			$1.8~V \leq V_{\text{DD}} < 2.7~V$			-10.0	mA
			$4.0~V \leq V_{\text{DD}} \leq 5.5~V$			-23.0	mA
			$2.7~V \leq V_{\text{DD}} < 4.0~V$			-20.0	mA
			$1.8~V \leq V_{\text{DD}} < 2.7~V$			-15.0	mA
	Іон2	Per pin for P20 to P27	$AV_{\text{REF}} \leq V_{\text{DD}}$			-0.1	mA

Notes 1. Value of current at which the device operation is guaranteed even if the current flows from EV_{DD} pin to an output pin.

2. Specification under conditions where the duty factor is 60% or 70%.

The output current value that has changed the duty ratio can be calculated with the following expression (when changing the duty factor from 70% to n%).

• Total output current of pins = $(I_{OH} \times 0.7)/(n \times 0.01)$

<Example> Where IOH = 20.0 mA and n = 50%

Total output current of pins = $(-20.0 \times 0.7)/(50 \times 0.01) = -28.0$ mA

However, the current that is allowed to flow into one pin does not vary depending on the duty factor. A current higher than the absolute maximum rating must not flow into one pin.

Caution P02 to P04 do not output high level in N-ch open-drain mode.

Remark Unless specified otherwise, the characteristics of alternate-function pins are the same as those of port pins.

(A) Grade Products

(2) Serial interface: Serial array unit (8/18)

 $(T_A = -40 \text{ to } +85^{\circ}\text{C}, 2.7 \text{ V} \le \text{V}_{DD} = \text{EV}_{DD} \le 5.5 \text{ V}, \text{V}_{SS} = \text{EV}_{SS} = \text{AV}_{SS} = 0 \text{ V})$

Parameter	Symbol		Conditions			TYP.	MAX.	Unit
Transfer rate		transmission	$4.0~V \leq V_{\text{DD}} \leq 5.5~V,$				Note 1	
			$2.7~V \leq V_b \leq 4.0~V$	fclк = 16.8 MHz, fмcк = fclк,			2.8 Note 2	Mbps
				C_{b} = 50 pF, R_{b} = 1.4 k\Omega, V_{b} = 2.7 V				
			$2.7~V \leq V_{\text{DD}} < 4.0~V,$				Note 3	
			$2.3~V \leq V_b \leq 2.7~V$	fclк = 19.2 MHz, fмcк = fclк,			1.2 Note 4	Mbps
				$C_b = 50 \text{ pF}, R_b = 2.7 \text{ k}\Omega, V_b = 2.3 \text{ V}$				

(e) Communication at different potential (2.5 V, 3 V) (UART mode) (dedicated baud rate generator output) (2/2)

Notes 1. The smaller maximum transfer rate derived by using fMCK/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 4.0 V \leq VDD = EVDD \leq 5.5 V and 2.7 V \leq Vb \leq 4.0 V

Maximum transfer rate =
$$\frac{1}{\{-C_b \times R_b \times \ln (1 - \frac{2.2}{V_b})\} \times 3}$$
 [bps]

Baud rate error (theoretical value) =
$$\frac{\frac{1}{|\text{Transfer rate} \times 2|} - \{-C_b \times R_b \times \ln(1 - \frac{2.2}{V_b})\}}{(\frac{1}{|\text{Transfer rate}|}) \times \text{Number of transferred bits}} \times 100 \,[\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

- 2. This value as an example is calculated when the conditions described in the "Conditions" column are met. Refer to Note 1 above to calculate the maximum transfer rate under conditions of the customer.
- 3. The smaller maximum transfer rate derived by using fMCK/6 or the following expression is the valid maximum transfer rate.

Expression for calculating the transfer rate when 2.7 V \leq VDD = EVDD < 4.0 V and 2.3 V \leq Vb \leq 2.7 V

Maximum transfer rate =
$$\frac{1}{\{-C_b \times R_b \times ln \ (1 - \frac{2.0}{V_b})\} \times 3}$$
 [bps]

Baud rate error (theoretical value) =
$$\frac{\frac{1}{\text{Transfer rate} \times 2} - \{-C_b \times R_b \times \ln(1 - \frac{2.0}{V_b})\}}{(\frac{1}{\text{Transfer rate}}) \times \text{Number of transferred bits}} \times 100 \,[\%]$$

* This value is the theoretical value of the relative difference between the transmission and reception sides.

4. This value as an example is calculated when the conditions described in the "Conditions" column are met. Refer to Note 3 above to calculate the maximum transfer rate under conditions of the customer.

Caution Select the TTL input buffer for RxD1 and the N-ch open drain output (VDD tolerance) mode for TxD1 by using the PIM0 and POM0 registers.

(Remark are given on the next page.)

					(9/3	33)
Chapter	Classification	Function	Details of Function	Cautions	Page	e
Chapter 6	Soft	Timer array unit	Channel output (TO0n pin) operation	 (2) Default level of TO0n pin and output level after timer operation start The following figure shows the TO0n pin output level transition when writing has been done in the state of TOE0n = 0 before port output is enabled and TOE0n = 1 is set after changing the default level. (a) When operation starts with TOM0n = 0 setting (toggle output) The setting of TOL0n is invalid when TOM0n = 0. When the timer operation starts after setting the default level, the toggle signal is generated and the output level of TO0n pin is reversed. (b) When operation starts with TOM0n = 1 setting (combination operation mode (PWM output)) When TOM0n = 1, the active level is determined by TOL0n setting. (3) Operation of TO0n pin in combination operation mode (TOM0n = 1) 	pp.211, 212	,
				 (a) When TOLOn setting has been changed during timer operation When the TOLOn setting has been changed during timer operation When the TOLOn setting has been changed during timer operation, the setting becomes valid at the generation timing of TOOn change condition. Rewriting TOLOn does not change the output level of TOOn. The following figure shows the operation when the value of TOLOn has been changed during timer operation (TOMOn = 1). (b) Set/reset timing To realize 0%/100% output at PWM output, the TOOn pin/TOOn set timing at master channel timer interrupt (INTTMOn) generation is delayed by 1 count clock by the slave channel. If the set condition and reset condition are generated at the same time, a higher priority is given to the latter. Figure 6-29 shows the set/reset operating statuses where the master/slave channels are set as follows. 	213	, _
			Collective manipulation of TO0n bits	When TOE0n = 1, even if the output by timer interrupt of each timer (INTTM0n) contends with writing to TO0n, output is normally done to TO0n pin.	p.215	
		Operation of timer array unit as	Input pulse interval measurement	The TI0k pin input is sampled using the operating clock selected with the CKS0n bit of the TMR0n register, so an error equal to the number of operating clocks occurs.	p.232	
		independent channel	Input signal high-/low-level width measurement	The TI0k pin input is sampled using the operating clock selected with the CKS0n bit of the TMR0n register, so an error equal to the number of operating clocks occurs.	p.236	
		Operation of plural channels of timer array unit	PWM function	To rewrite both TDR0n of the master channel and TDR0m of the slave channel, a write access is necessary two times. The timing at which the values of TDR0n and TDR0m are loaded to TCR0n and TRC0m is upon occurrence of INTTM0n of the master channel. Thus, when rewriting is performed split before and after occurrence of INTTM0n of the master channel, the TO0m pin cannot output the expected waveform. To rewrite both TDR0n of the master and TDR0m of the slave, therefore, be sure to rewrite both the registers immediately after INTTM0n is generated from the master channel.	p.240	
			One-shot pulse output function	The timing of loading of TDR0n of the master channel is different from that of TDR0m of the slave channel. If TDR0n and TDR0m are rewritten during operation, therefore, an illegal waveform is output. Rewrite the TDR0n after INTTM0n is generated and the TDR0m after INTTM0m is generated.	p.247	

						(29	/33)
Chantor	Cliapter	Classification	Function	Details of Function	Cautions	Pag	e
Chanter 07		Hard	Electrical specifications (standard products)	Recommended oscillator constants	The oscillator constants shown above are reference values based on evaluation in a specific environment by the resonator manufacturer. If it is necessary to optimize the oscillator characteristics in the actual application, apply to the resonator manufacturer for evaluation on the implementation circuit. When doing so, check the conditions for using the RMC register, and whether to enter or exit the STOP mode. The oscillation voltage and oscillation frequency only indicate the oscillator characteristic. Use the 78K0R/KE3 so that the internal operation conditions are within the specifications of the DC and AC characteristics.	p.714	
				DC	P02 to P04 do not output high level in N-ch open-drain mode.	p.715	
				characteristics	The maximum value of V_{H} of pins P02 to P04 is V_{DD} , even in the N-ch open-drain mode.	p.717	
					For P122/EXCLK, the value of V _{IH} and V _{IL} differs according to the input port mode or external clock mode. Make sure to satisfy the DC characteristics of EXCLK in external clock input mode.	p.717	
	,	oft		During	When using UART1, select the normal input buffer for RxD1 and the normal output	p.731	
		Sc		communication at same potential (UART mode) (dedicated baud rate generator output)	mode for TxD1 by using the PIM0 and POM0 registers.		1
				During communication at same potential (CSI mode) (master mode, SCKp internal clock output)	When using CSI10, select the normal input buffer for SI10 and the normal output mode for SO10 and SCK10 by using the PIM0 and POM0 registers.	p.732	
				During communication at same potential (CSI mode) (slave mode, SCKp external clock input)	When using CSI10, select the normal input buffer for SI10 and SCK10 and the normal output mode for SO10 by using the PIM0 and POM0 registers.	p.733	
				During communication at same potential (simplified I ² C mode)	Select the normal input buffer and the N-ch open drain output (V _{DD} tolerance) mode for SDA10 and the normal output mode for SCL10 by using the PIM0 and POM0 registers.	p.736	
				During communication at different potential (2.5 V, 3 V) (UART mode) (dedicated baud rate generator output)	Select the TTL input buffer for RxD1 and the N-ch open drain output (V_{DD} tolerance) mode for TxD1 by using the PIM0 and POM0 registers.	pp.737 738, 74	, 🗆 Ю